Solder Mask/ Covercoat

**Product Type:** Polymer Thick Film

**Product Name:** UVD5271

**Description**
UVD5271 is an UV curable solder mask, covercoat, or dielectric designed for rigid substrates. UVD5271 offers rapid curing combined with outstanding adhesion and resistance to solvents, moisture, and the soldering process. It is less sensitive to surface cleanliness than other UV curable materials. It offers excellent electrical and environmental integrity after soldering and cleaning, and outstanding fine line definition, typically ≥ 8 mils. Heraeus also offers a series of compatible, thermally cured conductors.

**Key Benefits**
- REACH¹ and RoHS² compliant
- High adhesion to many substrates
- Excellent chemical and solder resistance
- High insulation resistance and breakdown voltage

**Recommended Processing Guidelines**

**Printing:**
- 250 – 280 mesh screen
- 0.5 mil emulsion
- 0.02 inch snap-off.
- Clean uncured resin with Isopropanol or similar solvent.

**Curing:**
- 200 W/in Hg lamp, cure time <1 second and belt speed 8’/minute at 25 micron film thickness. Cures to a glossy hard film which is highly resistant to surface scratching.

**Thinner:**
- RV-825

**Warranty:**
Material guaranteed to meet specifications for 6 months from date of shipment

**Storage:**
Store in a dry location at 5 – 25 °C
- DO NOT REFRIGERATE.
- Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

**SPECIAL NOTE:**
Some of these materials may show resistance shifts due to thermal storage. Stability baking has been shown to minimize this behavior.

**Typical Properties**

**Form:**
- Dark Blue pseudoplastic paste intended for screen printing.

**Viscosity:**
10 – 30 Kcps; Brookfield HBT Spindle #14 @ 50 rpm, 25 °C

**Chemical Resistance:**
Excellent solvent resistance. Can be immersed for more than 15 minutes in halogenated hydrocarbons, acetone, and lower alcohols without degradation. Resistant to most dilute acids.

**Thermal Stability/Solder Resistance:**
- Withstands molten solder (250 °C) up to 30 minutes to assure 100% adhesion during normal soldering operations. Withstands a boiling water immersion for seven consecutive hours without degradation.

**Typical Dielectric Characteristics**

**Insulation Resistance:**
1 x 10¹³ Ω

**Dielectric Breakdown Voltage:**
> 1000 Volts/mil

**Hermeticity I.R.:**
1 X 10¹² ohms

**Leakage Current:**
30 picoamps

¹REACH: Registration, Evaluation, Authorization, and Restriction of Chemicals managed by the European Union.
²RoHS: Restriction of Hazardous Substances directive managed by the European Union.

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Legend:

1) REACH compliant according to the latest ** Annex XIV to Regulation (EC) of the European Parliament and of the council on the Registration, Evaluation, Authorisation and Restriction of Chemicals ("REACH") by European Chemicals Agency and its subsequent amendments; the material does not contain any substance listed in Annex XIV.

2) RoHS compliant according to the latest ** Directives (European Union) of Restriction of Hazardous Substances ("RoHS") and its subsequent amendments (including the exceptions related to Pb)

3) Properties for single print of 25 microns.

4) I.R. measured with water drop present.

5) Keithley electrometer, 1M NaCl solution, 4 hour immersion. Heraeus 5260 epoxy conductor